



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-01-24
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EBE3*0882AAY	A	ZY1A	2018-01-24
Amount	UoM	Unit type	ST ECOPACK Grade	
23.71	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	3x3x1	8	J bend	
Comment	Package: E3 MSOP/TSSOP 8 BODY3.00 PITCH0.65; MDF valid for TS882IYST			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	EBE3*0882AAY				4982298.0	999703.0				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	0.339	mg	supplier	die	Silicon (Si)	7440-21-3		0.319	mg	941003	13454				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	11799	169				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	2950	42				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	2950	42				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.008	mg	23599	337				
Leadframe	M-004 Copper and its alloys	10.673	mg	supplier	alloy	Copper (Cu)	7440-50-8		9.965	mg	933664	420287				
				supplier	alloy	Nickel (Ni)	7440-02-0		0.310	mg	29045	13075				
				supplier	alloy	Silicon (Si)	7440-21-3		0.068	mg	6371	2868				
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.015	mg	1405	633				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.305	mg	28577	12864				
	M-008 Precious metals			supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	468	211				
	M-008 Precious metals			supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	468	211				
Die attach	M-015 Other organic materials	0.324	mg	supplier	glue	Silver(Ag)	7440-22-4		0.246	mg	759259	10375				
				supplier	glue	Reaction product: bisphenol-F-(epichlorhydrin)	9003-36-5		0.022	mg	67901	928				
				supplier	glue	Fatty acids, C18-unsatd., dimers, polymers with	68475-94-5		0.013	mg	40123	548				
				supplier	glue	.gamma. Butyrolactone	96-48-0		0.013	mg	40123	548				
				supplier	glue	Polyoxyalkylene amine	9046-10-0		0.013	mg	40123	548				
				supplier	glue	Epoxy Resin	29690-82-2		0.013	mg	40123	548				
				supplier	glue	Epoxy Resin Modifier	Proprietary		0.002	mg	6173	84				
				supplier	glue	Substituted Silane	Proprietary		0.002	mg	6173	84				
				Bonding wires	M-008 Precious metals	0.081	mg	supplier	wire	Gold (Au)	7440-57-5		0.081	mg	1000000	3416
				Encapsulation	M-015 Other organic materials	12.292	mg	supplier	mold compound	Epoxy Resin	29690-82-2		1.045	mg	85015	44074
supplier	mold compound	Phenol Resin	205830-20-2						0.492	mg	40026	20751				
supplier	mold compound	Silica Amorphous A	60676-86-0						9.710	mg	789945	409532				
supplier	mold compound	Silica Amorphous B	7631-86-9						0.983	mg	79971	41459				
				supplier	mold compound	Carbon Black	1333-86-4		0.062	mg	5044	2615				